

Product Change Notification (PCN) Announcement

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Title	EMPV series change packing metohd notification	Date	2024/Dec/26	Ref No.	E240038-3
Models	EMPV-1201, EMPV-1202				
Level	○ Critical ● Major ○ Minor ○ Notice				

Description

This PCN is being issued to address that Innodisk EMPV-1201, EMPV-1202 series are going to change packing method to reduce possibility of collision.

New packing method will implement to standard P/N.

Old Packing



New Packing



Affected Component Table				
Model	Current Part Number	New Part Number		
EMPV-1201	EMPV-1201%			
EMPV-1202	EMPV-1202%			

Desc. Note

Innodisk anticipates no negative impact to customer's application.

There is no functional implication to customer's application but improve reliability, and qualification of these changes may not be necessary.

Note

No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones. Innodisk apologizes for any inconvenience caused by this and appreciate your understanding.

Innodisk promises that new items deliver quality and reliability for your application. If you have any further inquiry of our products or if you have any question about the specification of it, please contact Innodisk sales person.

Thank you for your confidence in Innodisk in the past and looking forward to serving you in the near future.

Key Milestone Dates	
Effective Date	2025/Jan/15

*Recommend action: Call back All stock rework Running change Cur	in Effective date	

Customer Impact of Change and Recommended Action

Please review the content and provide specific recommendation based on this document.

Innodisk anticipates no negative impact to customer's application. There is no functional implication to customer's application but improve reliability, and qualification of these changes may not be necessary.

Revision History				
Date of Revision:	Revision Number:	Remark:		
2024/Dec/26	E240038-3			

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